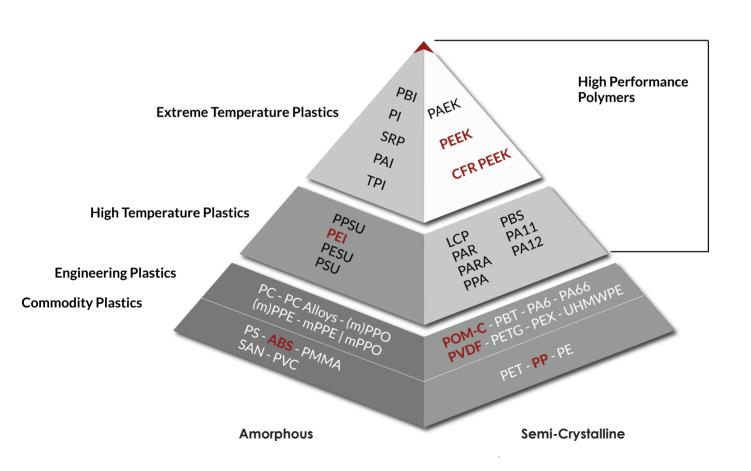


TECHNICAL GRADE MATERIALS

Apium Specialty Filaments - PEEK



High Performance Solutions

PEEK - Material Properties

Semi-Crystallinity of PEEK

PEEK is a semi-crystalline material. Semi-crystalline materials have distinct characteristics compared to amorphous materials. Semi-crystalline materials have well-defined melting point, good chemical, fatigue and wear resistance. Proper attention must be paid to the temperature control during printing to ensure it is regulated well to produce parts of consistent crystallinity with good properties.

Apium P220 Series 3D printers allow the printing of PEEK parts with 29-32% crystallinity, the closest ratio in the 3D printing industry to 35% crystallinity of injection moulded PEEK parts.

Characteristics of 3D Printed Semi-Crystalline PEEK

The professional PEEK 3D printers of Apium are capable of processing industrial grade PEEK filaments with the highest quality in 3D printing industry.

Characteristics of 3D printed PEEK with Apium's technology:

- High mechanical strength
- Good chemical resistance
- High temperature resistance
- Flame Retardant
- Lightweight
- Excellent wear resistance
- Good fatigue resistance



PEEK Filament - High Performance Semi-Crystalline Material











| MECHANICAL PROPERTIES | CONDITIONS | TEST METHOD | VALUE |
|---------------------------|---------------------|----------------|-------------|
| Tensile Strength XY | 23 °C, 48% Humidity | DIN EN ISO 527 | 77,2 MPa |
| Tensile Strength YZ | 23 °C, 48% Humidity | DIN EN ISO 527 | 85,4 MPa |
| Tensile Strength Z | 23 °C, 48% Humidity | DIN EN ISO 527 | 20,5 MPa |
| Tensile Elongation XY | 23 °C, 48% Humidity | DIN EN ISO 527 | 3 % |
| Tensile Elongation YZ | 23 °C, 48% Humidity | DIN EN ISO 527 | 2,6 % |
| Tensile Elongation Z | 23 °C, 48% Humidity | DIN EN ISO 527 | 0,6 % |
| Tensile Modulus XY | 23°C, 48% Humidity | DIN EN ISO 527 | 3 GPa |
| Tensile Modulus YZ | 23°C, 48% Humidity | DIN EN ISO 527 | 3,8 GPa |
| Tensile Modulus Z | 23°C, 48% Humidity | DIN EN ISO 527 | 3,2 GPa |
| Flexural Strength XY | 23°C, 48% Humidity | DIN EN ISO 527 | 31 MPa |
| Flexural Strength YZ | 23°C, 48% Humidity | DIN EN ISO 527 | 75,6 MPa |
| Flexural Strength Z | 23°C, 48% Humidity | DIN EN ISO 527 | 43,6 MPa |
| Flexural Modulus XY | 23 °C, 48% Humidity | DIN EN ISO 527 | 5,6 GPa |
| Flexural Modulus YZ | 23 °C, 48% Humidity | DIN EN ISO 527 | 7,7 GPa |
| Flexural Modulus Z | 23 °C, 48% Humidity | DIN EN ISO 527 | 10,6 GPa |
| Charpy Impact Strength XY | 23 °C, 48% Humidity | DIN EN ISO 179 | 34,88 kJ/m² |
| Charpy Impact Strength YZ | 23°C, 48% Humidity | DIN EN ISO 179 | 9,62 kJ/m² |
| Charpy Impact Strength Z | 23 °C, 48% Humidity | DIN EN ISO 179 | 2,94 kJ/m² |

High Performance Solutions

PEEK - Applications





Aerospace

PEEK is your lightweight material solution where manufacturing costs, durability in harsh environments and processing flexibility play a significant role. It offers great benefits for landing gear hubcaps, aircraft door handles, cable ties, composite fasteners, as housing for fire prone components and many more applications.



Automotive

PEEK exhibits an excellent combination of strength, durability and heat resistance. PEEK is the material solution where system weight, energy efficiency and a wide range of operating temperatures (-196°C to 260°C) play a significant role in your operations.



Oil & Gas

PEEK is the material of choice for your oil and gas applications which require high quality equipment and tool systems to extreme temperatures, corrosive fluids and gases, and high pressures. For antenna sleeves, valve seats, electrical connectors, primary seals, impellers and many more system components, benefit from the outstanding characteristics of PEEK.



Semiconductors and Electronics

For the two main properties requirements -electrical insulation and mechanical function- of your electronics applications being contact sockets, insulators, wafer carriers, chemical cleaning systems, etc., PEEK is the material of choice with its outstanding properties.

